

Title (en)

Subdivisible substrate and method of making the same

Title (de)

Mehrfach-Substrat sowie Verfahren zu seiner Herstellung

Title (fr)

Substrat subdivisible et son procédé de fabrication

Publication

EP 0627760 B1 19990908 (DE)

Application

EP 94107882 A 19940521

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- DE 4319944 A 19930616

Abstract (en)

[origin: EP0627760A1] The invention relates to a multiple substrate having a ceramic layer, which forms at least two panels adjacent to each other and connected to each other in one piece, each respective panel being provided with at least one metallisation or metallic surface on at least one surface side of the ceramic layer, and to a novel process for its production. <IMAGE>

IPC 1-7

H01L 21/00; B28D 5/00; H01L 21/48

IPC 8 full level

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CPC (source: EP US)

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Citation (examination)

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